

# TUSB211A USB 2.0 480Mbps 高速信号调节器

## 1 特性

- 宽电源电压范围：2.3V 至 6.5V
- 超低 USB 断开和关断功耗
- 可提供 USB 2.0 高速信号调节
- 兼容 USB 2.0、On-The-Go (OTG) 2.0 和电池充电 (BC) 1.2
- 支持低速、全速和高速信号传输
- 主机或器件无关
- 支持长达 5m 的电缆
  - 通过外部下拉电阻器值实现四种可选的信号 EQ (边沿升压与直流升压) 设置
- 支持长达 10m 的电缆和两台 TUSB211A 器件
- 可扩展解决方案 - 器件可通过菊花链连接用于高损耗应用
- 与 TUSB211/212/214/216/217A 引脚兼容 (3.3V)

## 2 应用

- 笔记本电脑、台式机或扩展坞
- 便携式电子产品
- 平板电脑
- 手机
- 电视
- 有源电缆、电缆扩展器、背板

## 3 说明

TUSB211A 是第三代 USB 2.0 高速信号调节器，旨在补偿传输通道中的交流损失（由于电容性负载）和直流损失（由于电阻性负载）。

TUSB211A 采用了专利设计，可通过边缘加速器来对 USB 2.0 高速信号的传输边缘进行加速，并通过直流升压功能来提高静态电平。

此外，TUSB211A 还具有预均衡功能，可补偿较长电缆应用中的码间串扰 (ISI) 抖动。USB 低速和全速信号特征不受 TUSB211A 的影响。

TUSB211A 可在不改变数据包计时或不增加传播延迟的情况下提高信号质量。

TUSB211A 可使用长达 5 米的线缆帮助系统通过 USB 2.0 高速近端眼图合规性测试。

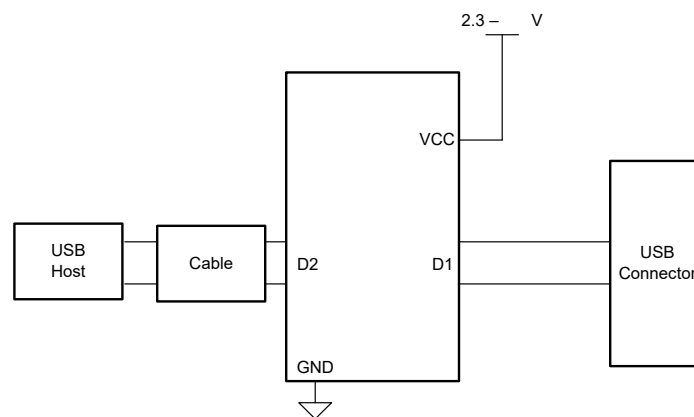
TUSB211A 与 USB On-The-Go (OTG) 和电池充电 (BC) 协议兼容。

### 器件信息

器件型号	封装 <sup>(1)</sup>	OP TEMP (T <sub>A</sub> ) °C	封装尺寸 (标称值) <sup>(2)</sup>
TUSB211A	RWB (X2QFN, 12)	0 至 70	1.6mm x 1.6mm
TUSB211AI		-40 至 85	

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

(2) 封装尺寸 (长 x 宽) 为标称值，不包括引脚。



简化原理图



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## 4 Revision History

DATE	REVISION	NOTES
September 2023	*	Initial Release

## 5 Pin Configuration and Functions

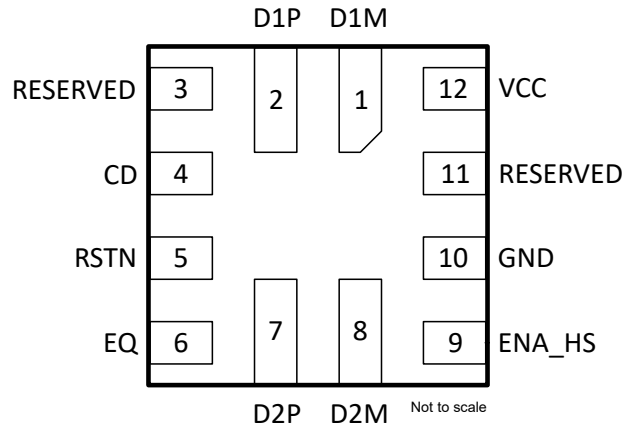


图 5-1. TUSB211A RWB 12-Pin X2QFN (Top View)

表 5-1. Pin Functions

PIN		TYPE <sup>(1)</sup>	INTERNAL PULLUP/PULLDOWN	DESCRIPTION
NAME	NO.			
EQ	6	I	N/A	USB High-speed EQ select via external pull down resistor. Both edge boost and DC boost are controlled by a single pin. Sampled upon power up. Does not recognize real time adjustments. Auto selects EQ LEVEL = 3 when left floating.
RESERVED	11	I	500 k $\Omega$ PU	Reserved pin for TI test purposes. Leave floating or connect external capacitor to GND for normal operation.
ENA_HS	9	I/O	N/A	After reset: Output signal ENA_HS. Flag indicating that channel is in High-speed mode. Asserted upon: 1. Detection of USB-IF High-speed test fixture from an unconnected state followed by transmission of USB TEST_PACKET pattern. 2. Squelch detection following USB reset with a successful HS handshake [HS handshake is declared to be successful after single chirp J chirp K pair where each chirp is within 18 $\mu$ s - 128 $\mu$ s].
D2P	7	I/O	N/A	USB High-speed positive port.
D2M	8	I/O	N/A	USB High-speed negative port.
GND	10	P	N/A	Ground
D1M	1	I/O	N/A	USB High-speed negative port.
D1P	2	I/O	N/A	USB High-speed positive port.
RESERVED	3	I/O	500 k $\Omega$ PU 1.8 M $\Omega$ PD	Reserved pin for TI test purposes. Leave floating for normal operation.
VCC	12	P	N/A	Supply power
RSTN	5	I	500 k $\Omega$ PU 1.8 M $\Omega$ PD	Device disable/enable. Low - Device is at reset and in shutdown, and High - Normal operation. Recommend 0.1- $\mu$ F external capacitor to GND to ensure clean power on reset if not driven. If the pin is driven, it must be held low until the supply voltage for the device reaches within specifications.
CD	4	O	When RSTN asserted there is a 500 k $\Omega$ PD	After reset: Output CD. Flag indicating that a USB device is attached (connection detected). Asserted from an unconnected state upon detection of DP or DM pull-up resistor. De-asserted upon detection of disconnect.

(1) I = input, O = output, P = power

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
Supply voltage range	VCC	- 0.3	7	V
Voltage range USB data	DxP, DxM	- 0.3	5.5	V
Voltage range on EQ pin	EQ	-0.3	1.98	V
Voltage range other pins	RSTN	-0.3	5.5	V
Storage temperature, T <sub>stg</sub>		- 65	150	°C
Maximum junction temperature, T <sub>J(max)</sub>			125	°C

- (1) Operation outside the *Absolute Maximum Rating* may cause permanent device damage. *Absolute Maximum Rating* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Condition*. If used outside the *Recommended Operating Condition* but within the *Absolute Maximum Rating*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(2)</sup>	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 <sup>(3)</sup>	±750	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.  
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2.3	5	6.5	V
T <sub>A</sub>	Operating free-air temperature (TUSB211A)	0		70	°C
	Operating free-air temperature (TUSB211AI)	- 40		85	°C
T <sub>J</sub>	Junction temperature (TUSB211A)			85	°C
	Junction temperature (TUSB211AI)			105	°C
DxP, DxM	Voltage range USB data	0		3.6	V
EQ	Voltage range EQ pin	0		1.98	V
DIGITAL	Voltage range other pins (RSTN)	0		3.6	V

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		RWB (X2QFN)	UNIT
		12 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	137.4	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	62	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	67.2	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	1.9	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	67.3	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

Over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>POWER</b>						
I <sub>ACTIVE_HS</sub>	High Speed Active Current	USB channel = HS mode. 480 Mbps traffic. V <sub>CC</sub> supply stable, with EQ = Max		22	36	mA
I <sub>IDLE_HS</sub>	High Speed Idle Current	USB channel = HS mode, no traffic. V <sub>CC</sub> supply stable, EQ = Max		22	36	mA
I <sub>HS_SUSPEND</sub>	High Speed Suspend Current	USB channel = HS Suspend mode. V <sub>CC</sub> supply stable		0.75	1.4	mA
I <sub>FS</sub>	Full-Speed Current	USB channel = FS mode, 12 Mbps traffic, V <sub>CC</sub> supply stable		0.75	1.4	mA
I <sub>DISCONN</sub>	Disconnect Power	Host side application. No device attachment.		0.80	1.4	mA
I <sub>SHUTDOWN</sub>	Shutdown Power	RSTN driven low, V <sub>CC</sub> supply stable		60	115	μA
<b>CONTROL PIN LEAKAGE</b>						
I <sub>LKG_FS</sub>	Pin failsafe leakage current for RSTN	V <sub>CC</sub> = 0 V, pin at V <sub>IH,max</sub>		10	15	μA
<b>INPUT RSTN</b>						
V <sub>IH</sub>	High level input voltage		1.5		3.6	V
V <sub>IL</sub>	Low-level input voltage		0		0.5	V
I <sub>IH</sub>	High level input current	V <sub>IH</sub> = 3.6 V, R <sub>PU</sub> enabled			±15	μA
I <sub>IL</sub>	Low level input current	V <sub>IL</sub> = 0V, R <sub>PU</sub> enabled			±20	μA
<b>INPUT EQ</b>						
R <sub>EQ_LVL0</sub>	External pulldown resistor for EQ Level 0				160	Ω
R <sub>EQ_LVL1</sub>	External pulldown resistor for EQ Level 1		1.5	1.8	2	kΩ
R <sub>EQ_LVL2</sub>	External pulldown resistor for EQ Level 2		3.4	3.6	3.96	kΩ
R <sub>EQ_LVL3</sub>	External pulldown resistor for EQ Level 3 to remove upper limit for resistor value, can be left open		7.5			kΩ
<b>OUTPUTS CD, ENA_HS</b>						
V <sub>OH</sub>	High level output voltage for CD and ENA_HS	I <sub>O</sub> = - 50 μA, V <sub>CC</sub> ≥ 3.0 V	2.5			V
V <sub>OH</sub>	High level output voltage for CD	I <sub>O</sub> = - 25 μA, V <sub>CC</sub> = 2.3 V	1.7			V
V <sub>OH</sub>	High level output voltage for ENA_HS	I <sub>O</sub> = - 25 μA, V <sub>CC</sub> = 2.3 V	1.8			V
V <sub>OL</sub>	Low level output voltage for CD and ENA_HS	I <sub>O</sub> = 50 μA			0.3	V
<b>DxP, DxM</b>						
C <sub>IO_DXX</sub>	Capacitance to GND	Measured with VNA at 240 MHz, V <sub>CC</sub> supply stable, Redriver off		2.5		pF

(1) All typical values are at V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

## 6.6 Switching Characteristics

Over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>DxP, DxM USB Signals</b>						
F <sub>BR_DXX</sub>	Bit Rate	USB channel = HS mode. 480 Mbps traffic. V <sub>CC</sub> supply stable			480	Mbps
t <sub>R/F_DXX</sub>	Rise/Fall time		100			ps

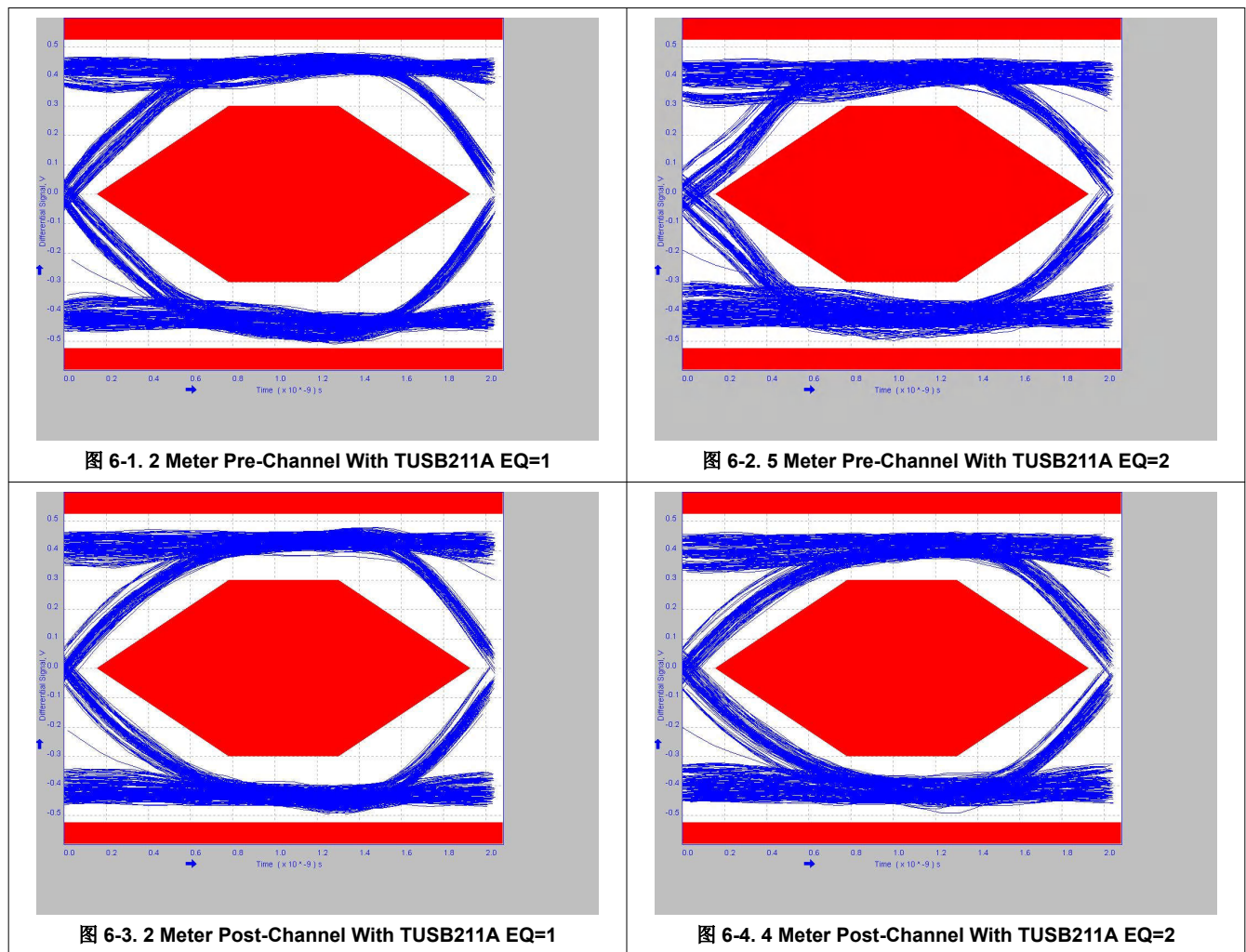
(1) All typical values are at V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

## 6.7 Timing Requirements

		MIN	NOM	MAX	UNIT
<b>POWER UP TIMING</b>					
$T_{RSTN\_PW}$	Minimum width to detect a valid RSTN signal assert when the pin is actively driven low	100			$\mu$ s
$T_{STABLE}$	VCC must be stable before RSTN de-assertion	300			$\mu$ s
$T_{READY}$	Maximum time needed for the device to be ready after RSTN is de-asserted.			500	$\mu$ s
$T_{RAMP}$	$V_{CC}$ ramp time			100	ms
$T_{RAMP}$	$V_{CC}$ ramp time	0.2			ms

## 6.8 Typical Characteristics

The typical characteristics shown in this section apply to near-end eye measurements taken at nominal conditions. The eyes are measured with various pre-channel cable lengths applied at the input or post-channel cable lengths applied at the output of the TUSB211A as indicated.



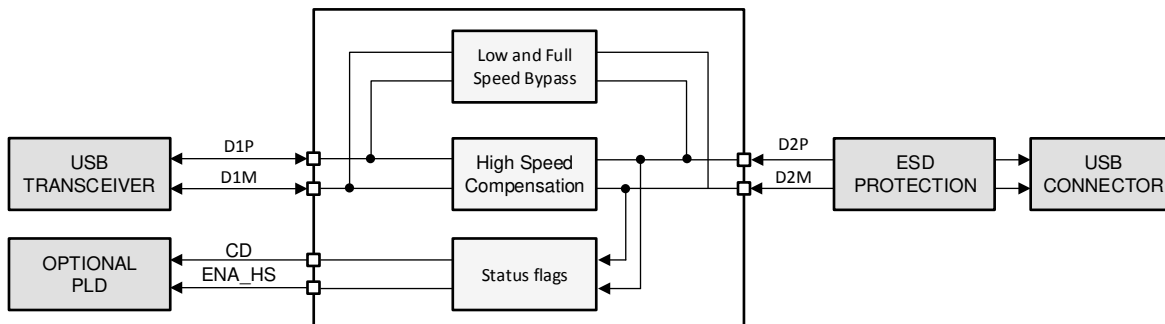
## 7 Detailed Description

### 7.1 Overview

The TUSB211A is a USB High-Speed (HS) signal conditioner designed to compensate for ISI signal loss in a transmission channel. TUSB211A has a patented design for USB Low Speed (LS) and Full Speed (FS) signals. It does not alter the signal characteristics. HS signals are compensated. The design is compatible with USB On-The-Go (OTG) and Battery Charging (BC) specifications.

Programmable signal gain through an external resistor permits fine tuning device performance to optimize signals. This helps pass USB HS electrical compliance tests at the connector. The TUSB211A allows application in series to cover longer distances, or high loss transmission paths. A maximum of 4 devices can be daisy-chained.

### 7.2 Functional Block Diagram



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### 7.3 Feature Description

#### 7.3.1 High-Speed EQ

The high-speed EQ (combination of edge boost and DC boost) improves the eye width for USB2.0 high-speed signals. It is direction independent and by that is compatible to OTG systems. The EQ pin is configuring the EQ strength with different values of pull down resistors to set 4 levels of EQ.

### 7.4 Device Functional Modes

#### 7.4.1 Low-Speed (LS) Mode

TUSB211A automatically detects an LS connection and does not enable signal compensation. CD pin is asserted high but ENA\_HS will be low.

#### 7.4.2 Full-Speed (FS) Mode

TUSB211A automatically detects an FS connection and does not enable signal compensation. CD pin is asserted high but ENA\_HS will be low.

#### 7.4.3 High-Speed (HS) Mode

TUSB211A automatically detects an HS connection and will enable signal compensation as determined by the external pull down resistance on its EQ pin.

CD pin and ENA\_HS pin are asserted high when high-speed EQ is active.

#### 7.4.4 High-Speed Downstream Port Electrical Compliance Test Mode

TUSB211A will detect an HS compliance test fixture and enter the downstream port high-speed eye diagram test mode. CD pin will be low and ENA\_HS pin is asserted high when TUSB211A is in HS eye compliance test mode.

If the RSTN pin is asserted low and de-asserted high while TUSB211A is operating in HS functional mode, then TUSB211A will transition to HS eye compliance test mode, the CD asserts low, and ENA\_HS remains high. When all this occurs, signal compensation is enabled.

### 7.4.5 Shutdown Mode

TUSB211A can be disabled when its RSTN pin is asserted low. DP, DM traces are continuous through the device in shutdown mode. The USB channel is still fully operational, but there is neither signal compensation, nor any indication from the CD pin as to the status of the channel.

**表 7-1. CD and ENA\_HS Pins in Different Modes**

MODE	CD	ENA_HS
Low-speed	HIGH	LOW
Full-speed	HIGH	LOW
High-speed	HIGH	HIGH
High-speed downstream port electrical test	LOW	HIGH
Shutdown	LOW	LOW



## 8 Application and Implementation

### 备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

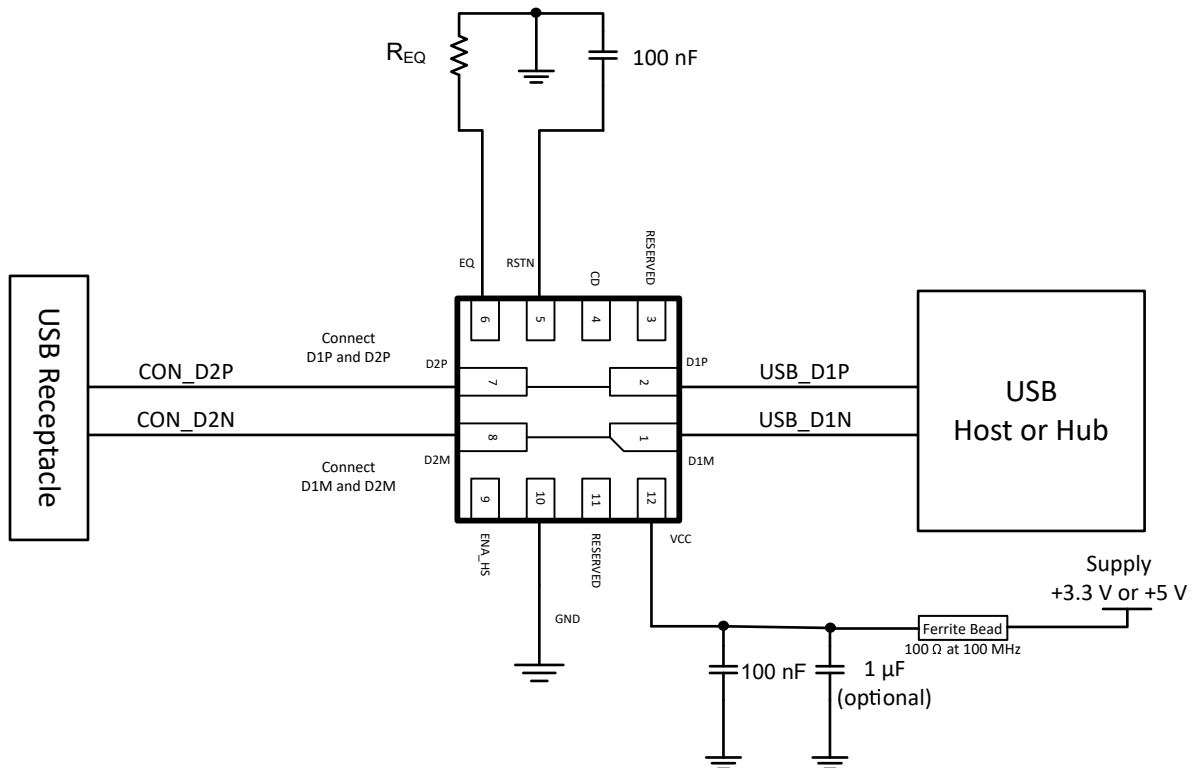
### 8.1 Application Information

The purpose of the TUSB211A is to restore the signal integrity of a USB High-speed channel up to the USB connector. The loss in signal quality stems from reduced channel bandwidth due to high loss PCB trace and other components that contribute a capacitive load. This can cause the channel to fail the USB near end eye mask. Proper use of the TUSB211A can help to pass this eye mask.

A secondary purpose is to use the CD pin of the TUSB211A to control other blocks on the customer platform, if so desired.

### 8.2 Typical Application

A typical application for TUSB211A is shown in 图 8-1. In this setup, D2P and D2M face the USB connector while D1P and D1M face the USB host. The orientation may be reversed [that is, D2 faces transceiver and D1 faces connector].



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图 8-1. TUSB211A Reference Schematic

## 8.2.1 Design Requirements

TUSB211A requires a valid reset signal as described in the *Power Supply Recommendations* section. The capacitor at RSTN pin is not required if a micro controller drives the RSTN pin according to recommendations.

For this design example, use the parameters provided in [表 8-1](#).

**表 8-1. Design Parameters for 3.3-V Supply With Low to Medium Loss System**

PARAMETER			VALUE <sup>(1)</sup>
V <sub>CC</sub>			3.3 V ±10%
I <sup>2</sup> C support required in system (Yes/No)			No
Edge and DC Boost	<b>R<sub>EQ</sub></b>	<b>EQ Level</b>	EQ Level 0: R <sub>EQ</sub> = 0-Ω
	0-Ω	0	
	1.8 kΩ ±1%	1	
	3.6 kΩ ±1%	2	
Do Not Install (DNI)		3	

- (1) These parameters are starting values for a low to medium loss system. Further tuning might be required based on specific host or device as well as cable length and loss profile. These settings are not specific to a 3.3-V supply system and could be applicable to 5-V supply system as well.

## 8.2.2 Detailed Design Procedure

The ideal EQ setting is dependent upon the signal chain loss characteristics of the target platform. The recommendation is to start with EQ Level 0, and then increment to EQ Level 1, and so on.

For the TUSB211A to recognize any change to the EQ setting, the RSTN pin must be toggled. This is because the EQ pin is latched on power up and the pin is ignored thereafter.

Placement of the device is also dependent on the application goal. [表 8-2](#) describes TI recommendations.

**表 8-2. Platform Placement Guideline**

PLATFORM GOAL	SUGGESTED TUSB211A PLACEMENT
Pass USB Near End Mask at the receptacle	Close to measurement point (connector)
Pass USB Far End Eye Mask at the plug	Close to USB PHY
Cascade multiple TUSB211As to improve device enumeration	Midway between each USB interconnect

**表 8-3. Table of Recommended Settings**

EQ settings <sup>(1)</sup> for channel loss	
Pre-channel cable length (Between USB PHY and TUSB211A)	EQ
0-3 meter	Level 0
2-5 meter	Level 1
Post-channel cable length (Between TUSB211A and inter-connect)	EQ
0-2 meter	Level 0
1-4 meter	Level 1

- (1) These parameters are starting values for different cable lengths. Further tuning might be required based on specific host or device as well as cable length and loss profile.

### 8.2.2.1 Test Procedure to Construct USB High-Speed Eye Diagram

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#### 备注

USB-IF certification tests for High-speed eye masks require the *mandated use* of the USB-IF developed test fixtures. These test fixtures do not require the use of oscilloscope probes. Instead they use SMA cables. More information can be found at the USB-IF Compliance Updates Page. It is located under the *Electrical Specifications* section, ID 86 dated March 2013.

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The following procedure must be followed before using any oscilloscope compliance software to construct a USB High-speed Eye Mask:

#### 8.2.2.1.1 For a Host Side Application

1. Configure the TUSB211A to the desired EQ setting.
2. Power on (or toggle the RSTN pin if already powered on) the TUSB211A.
3. Using SMA cables, connect the oscilloscope and the USB-IF host-side test fixture to the TUSB211A.
4. Enable the host to transmit USB TEST\_PACKET.
5. Execute the oscilloscope USB compliance software.
6. Repeat the above steps to re-test TUSB211A with a different EQ setting (must reset to change).

#### 8.2.2.1.2 For a Device Side Application

1. Configure the TUSB211A to the desired EQ setting.
2. Power on (or toggle the RSTN pin if already powered on) the TUSB211A.
3. Connect a USB host, the USB-IF device-side test fixture, and USB device to the TUSB211A. Ensure that the USB-IF device test fixture is configured to the 'INIT' position.
4. Allow the host to enumerate the device.
5. Enable the device to transmit USB TEST\_PACKET.
6. Using SMA cables, connect the oscilloscope to the USB-IF device-side test fixture and ensure that the device-side test fixture is configured to the 'TEST' position.
7. Execute the oscilloscope USB compliance software.
8. Repeat the above steps to re-test TUSB211A with a different EQ setting (must reset to change).

### 8.2.3 Application Curves

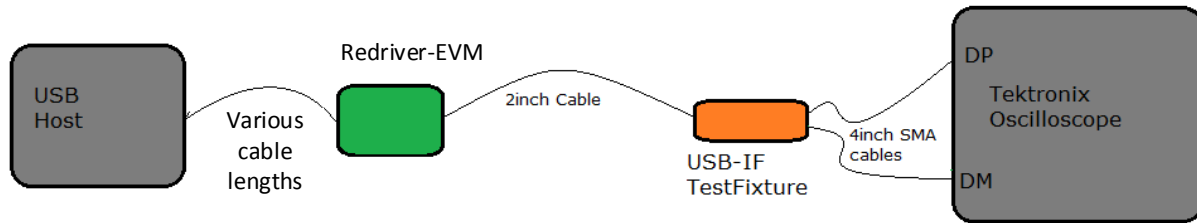


图 8-2. Near End Eye Measurement Set-Up With Pre-Channel Cable

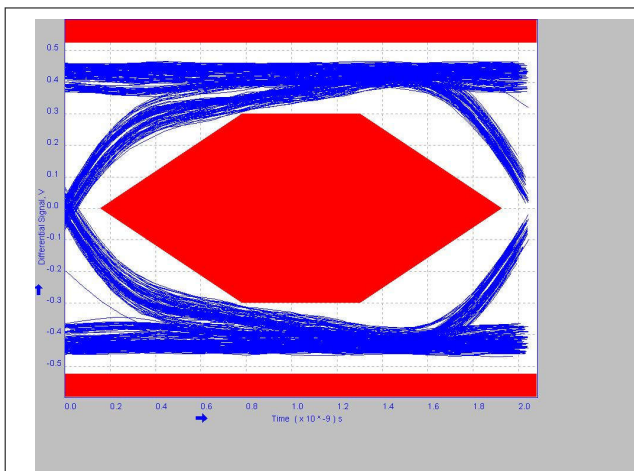


图 8-3. 2 Meter Pre-Channel Without TUSB211A

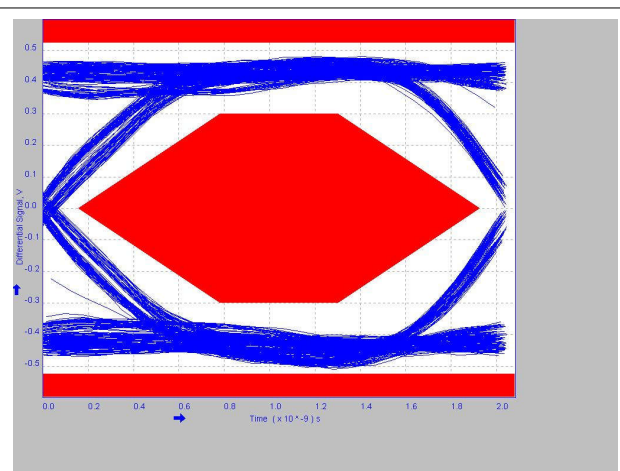


图 8-4. 2 Meter Pre-Channel With TUSB211A EQ=1

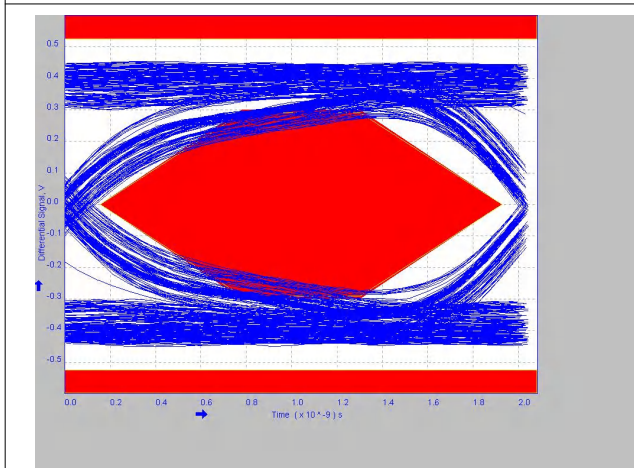


图 8-5. 5 Meter Without TUSB211A

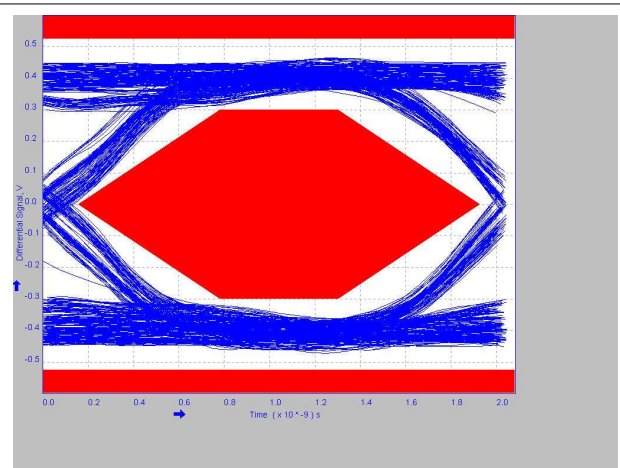


图 8-6. 5 Meter Pre-Channel With TUSB211A EQ=1

### 8.2.3 Application Curves (continued)

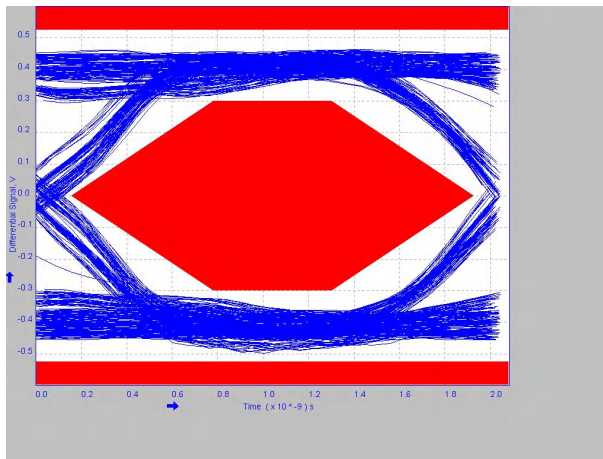


图 8-7. 5 Meter Pre-Channel With TUSB211A EQ=2

### 8.2.3 Application Curves

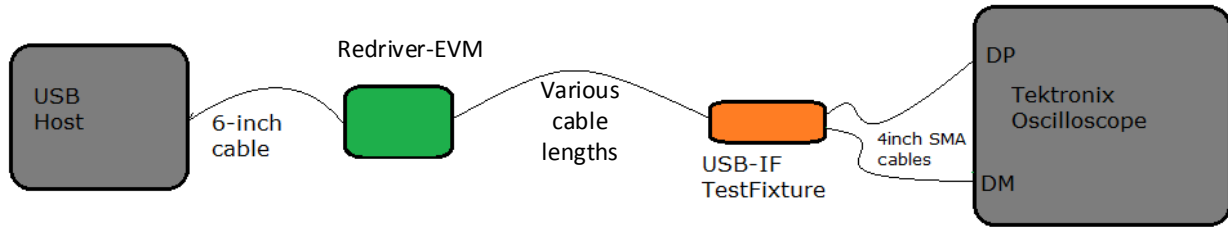


图 8-8. Near End Eye Measurement Set-Up With Post-Channel Cable

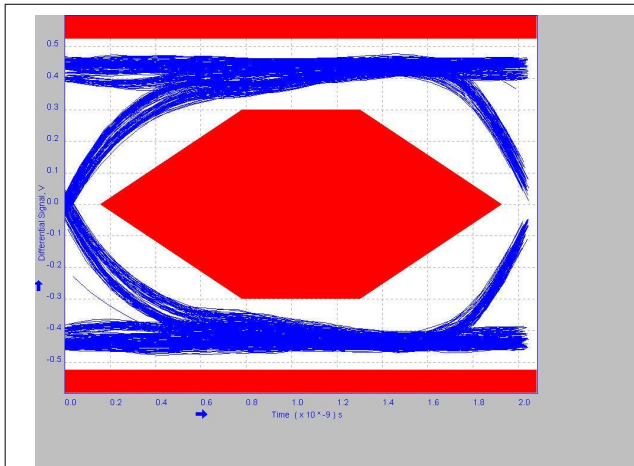


图 8-9. 1 Meter Post-Channel Without TUSB211A

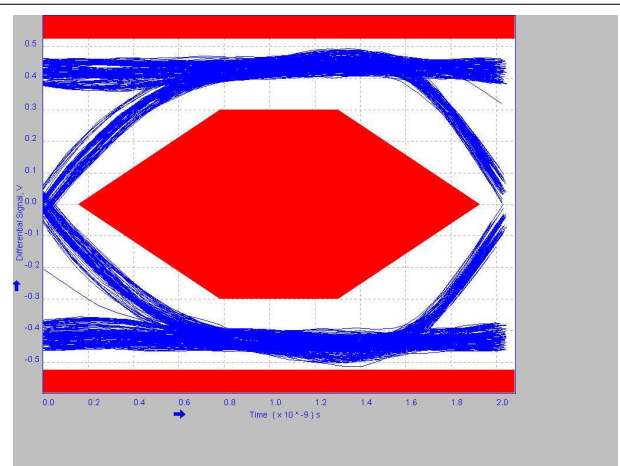


图 8-10. 1 Meter Post-Channel With TUSB211A EQ=0

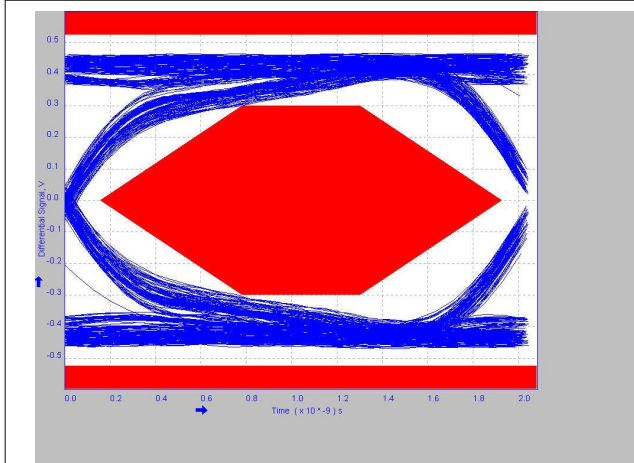


图 8-11. 2 Meter Post-Channel Without TUSB211A

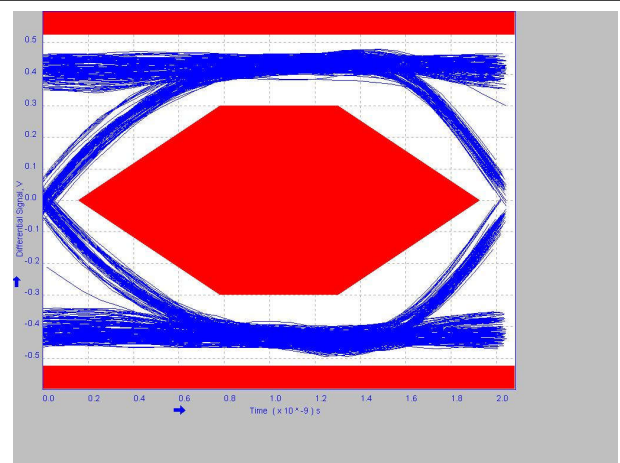


图 8-12. 2 Meter Post-Channel With TUSB211A EQ=1

### 8.2.3 Application Curves (continued)

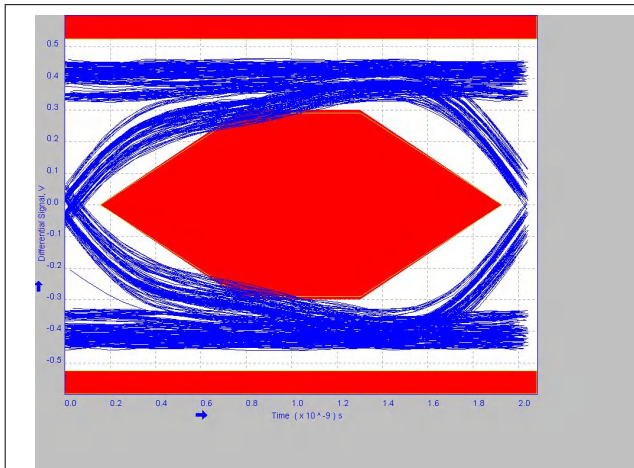


图 8-13. 4 Meter Post-Channel Without TUSB211A

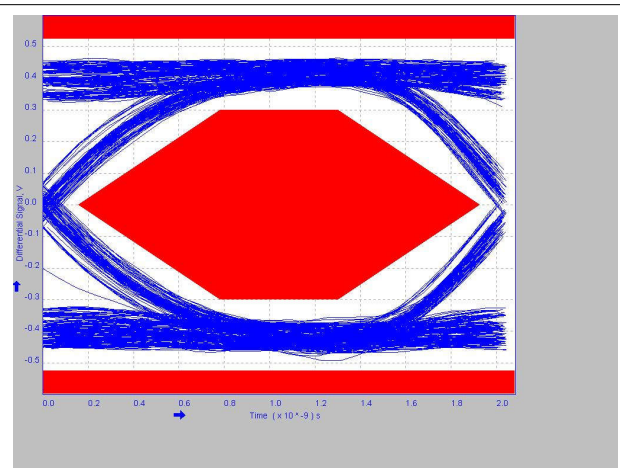


图 8-14. 4 Meter Post-Channel With TUSB211A EQ=2

## 8.3 Power Supply Recommendations

On power up, the interaction of the RSTN pin and power on ramp could result in digital circuits not being set correctly. The device should not be enabled until the power on ramp has settled to the minimum recommended supply voltage or higher for a correct power on reset of the digital circuitry. If RSTN cannot be held low by microcontroller or other circuitry until the power on ramp has settled, then an external capacitor from the RSTN pin to GND is required to hold the device in the low power reset state.

The RC time constant should be larger than five times of the power on ramp time (0 to  $V_{CC}$ ). With a typical internal pullup resistance of  $500\text{ k}\Omega$ , the recommended minimum external capacitance is calculated as:

$$[\text{Ramp Time} \times 5] \div [500\text{ k}\Omega] \quad (1)$$

## 8.4 Layout

### 8.4.1 Layout Guidelines

Although the land pattern has matched trace width to pad width, optimal impedance control is based on the user's own PCB stack-up. The recommendation is to maintain  $90\ \Omega$  differential routing underneath the device.



### 8.4.2 Layout Example

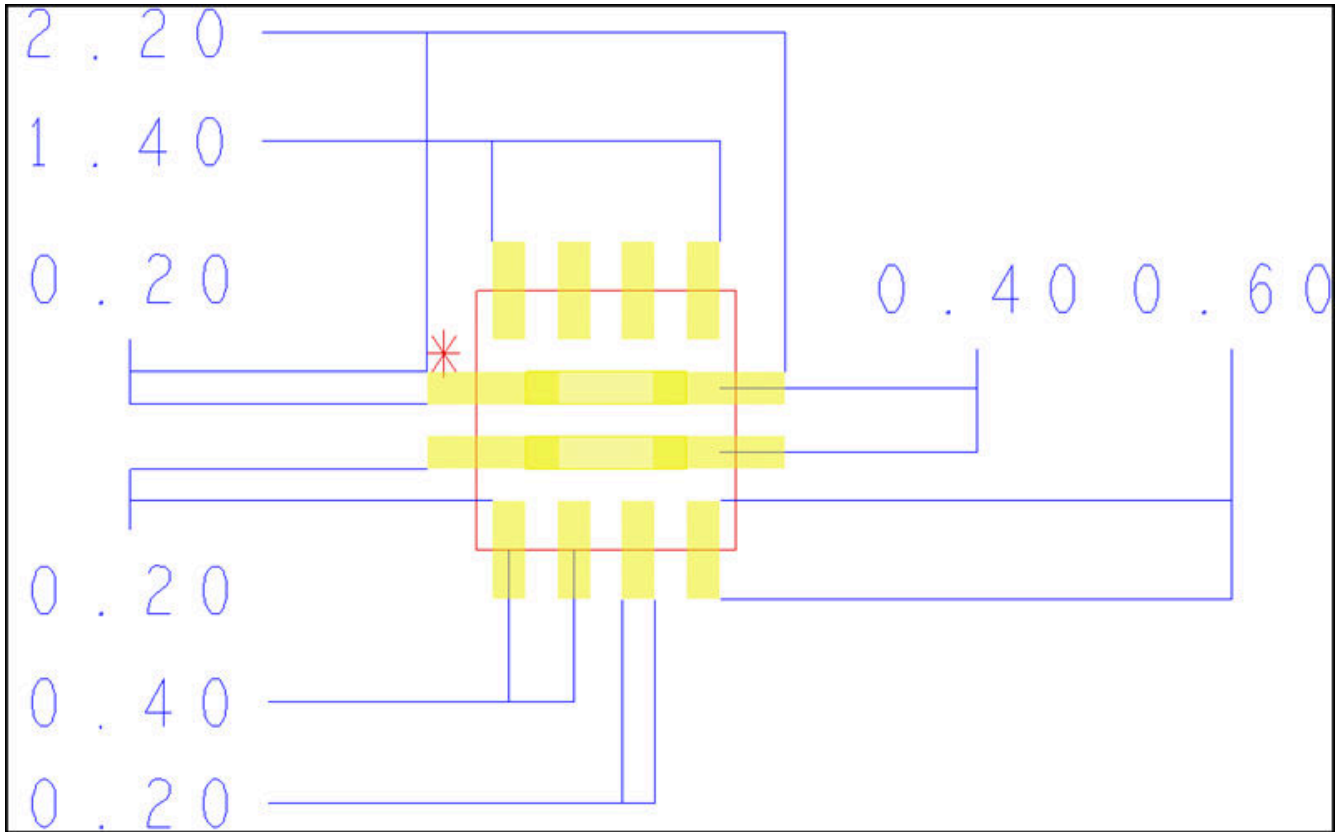


图 8-15. DP and DM Routing Underneath Device Package



## 9 Device and Documentation Support

### 9.1 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 9.2 支持资源

**TI E2E™ 支持论坛**是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《[使用条款](#)》。

### 9.3 Trademarks

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所有商标均为其各自所有者的财产。

### 9.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 9.5 术语表

**TI 术语表** 本术语表列出并解释了术语、首字母缩略词和定义。

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TUSB211AIRWBR	ACTIVE	X2QFN	RWB	12	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	1A	<a href="#">Samples</a>
TUSB211ARWBR	ACTIVE	X2QFN	RWB	12	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	1A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



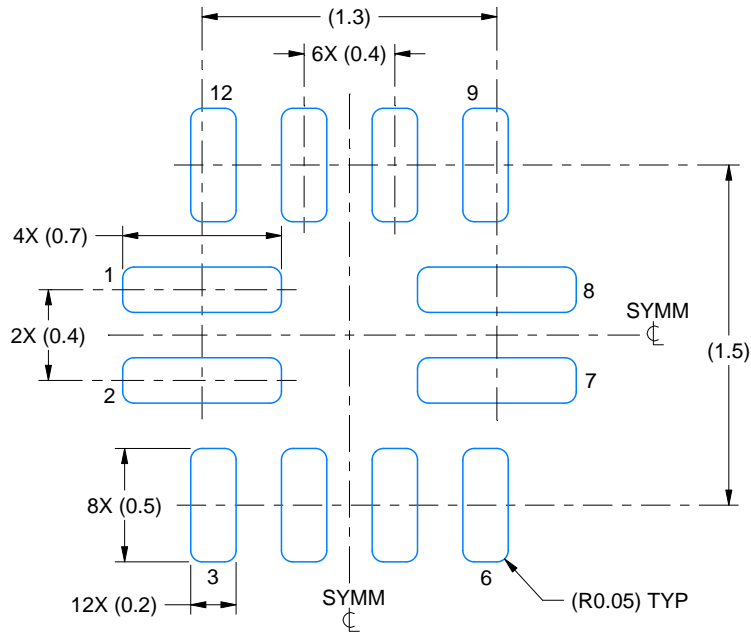


# EXAMPLE BOARD LAYOUT

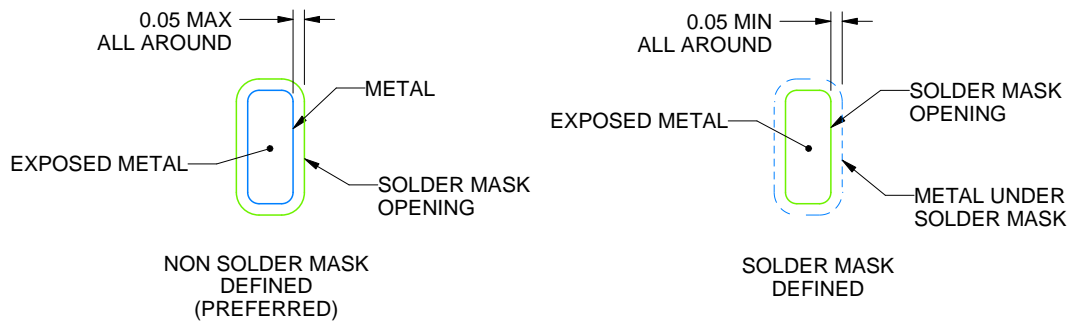
RWB0012A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:30X



SOLDER MASK DETAILS

4221631/B 07/2017

NOTES: (continued)

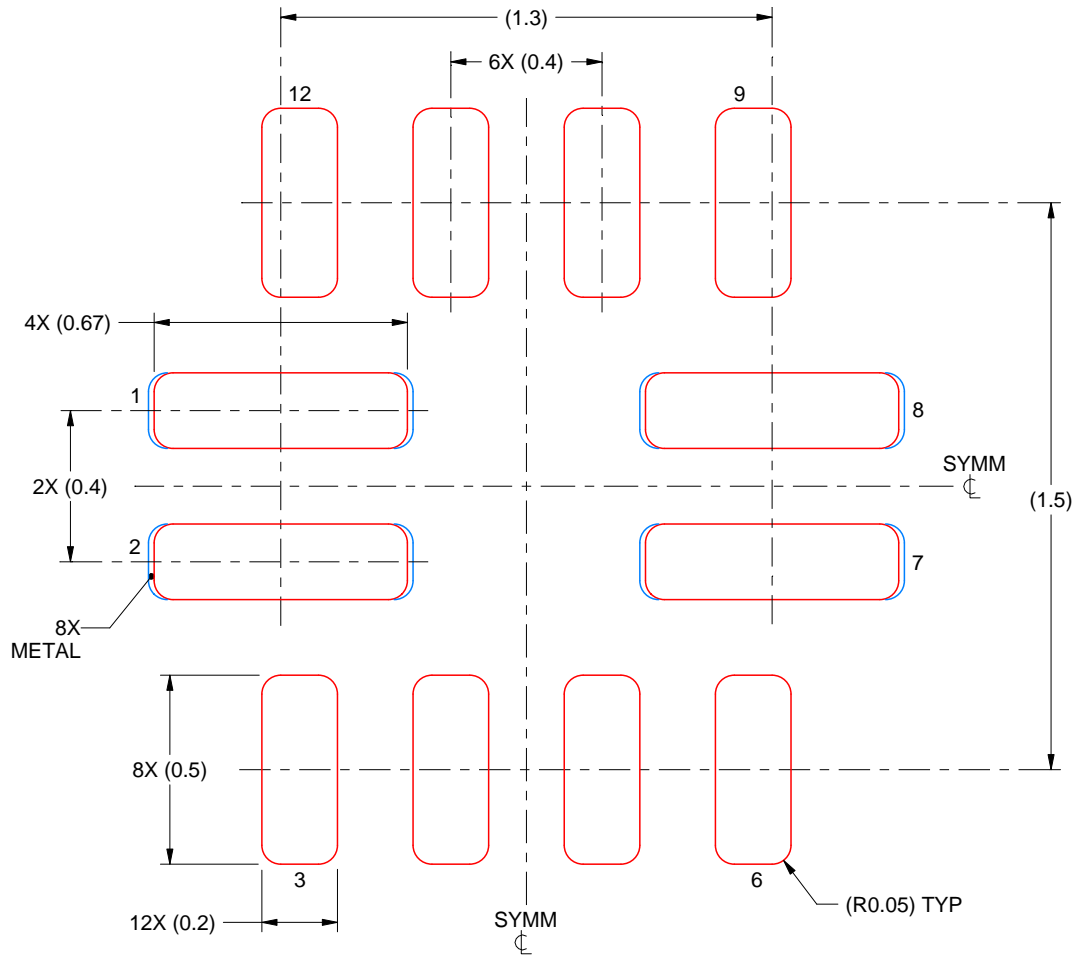
3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

RWB0012A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.1 mm THICK STENCIL  
PADS 1,2,7 & 8  
96% PRINTED SOLDER COVERAGE BY AREA  
SCALE:50X

4221631/B 07/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## 重要声明和免责声明

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